

**MSC030SDA120B**  
**Datasheet**  
**Zero Recovery Silicon Carbide Schottky Diode**

Final  
January 2018



# Contents

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1	Revision History .....	1
1.1	Revision A .....	1
2	Product Overview .....	2
2.1	Features .....	2
2.2	Benefits .....	2
2.3	Applications .....	2
3	Electrical Specifications .....	3
3.1	Absolute Maximum Ratings .....	3
3.2	Electrical Performance .....	4
3.3	Performance Curves .....	5
4	Package Specification .....	7
4.1	Package Outline Drawing .....	7

# 1 **Revision History**

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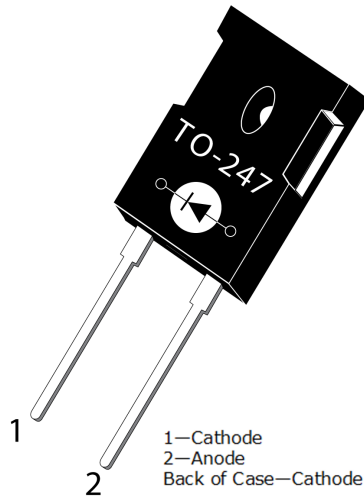
The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

## 1.1 **Revision A**

Revision A was published in January 2018. It is the first publication of this document.

## 2 Product Overview

The silicon carbide (SiC) power Schottky barrier diodes (SBD) product line from Microsemi increases your performance over silicon diode solutions while lowering your total cost of ownership for high-voltage applications. The MSC030SDA120B is a 1200 V, 30 A SiC SBD in a two-lead TO-247 package shown below.



### 2.1 Features

The following are key features of the MSC030SDA120B device:

- Low forward voltage
- Low leakage current
- No reverse recovery current/no forward recovery
- Avalanche energy rated
- RoHS compliant

### 2.2 Benefits

The following are benefits of the MSC030SDA120B device:

- Higher-reliability systems
- Minimizes heat sink requirements
- Higher efficiency

### 2.3 Applications

The MSC030SDA120B device is designed for the following applications:

- H/EV powertrain and EV charger
- Power supply and distribution
- PV inverter, converter, and industrial motor drives
- Smart grid transmission and distribution
- Aviation

### 3 Electrical Specifications

This section details the electrical specifications for the MSC030SDA120B device.

#### 3.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings for the MSC030SDA120B device.

All Ratings:  $T_c = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

**Table 1 • Absolute Maximum Ratings**

Symbol	Parameter	Ratings		Unit
V <sub>R</sub>	Maximum DC reverse voltage	1200		V
V <sub>RRM</sub>	Maximum peak repetitive reverse voltage			
V <sub>RWM</sub>	Maximum working peak reverse voltage			
I <sub>F</sub>	Maximum DC forward current	T <sub>C</sub> = 25 °C	65	A
		T <sub>C</sub> = 135 °C	29	
		T <sub>C</sub> = 145 °C	24	
I <sub>FRM</sub>	Repetitive peak forward surge current (T <sub>C</sub> = 25 °C, t <sub>p</sub> = 8.3 ms, half sine wave)	92		
I <sub>FSM</sub>	Non-repetitive forward surge current (T <sub>C</sub> = 25 °C, t <sub>p</sub> = 8.3 ms, half sine wave)	165		
P <sub>TOT</sub>	Power dissipation	T <sub>C</sub> = 25 °C	259	W
		T <sub>C</sub> = 110 °C	112	
T <sub>J</sub> , T <sub>STG</sub>	Operating junction and storage temperature range	−55 to 175		°C
T <sub>L</sub>	Lead temperature for 10 seconds	300		
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, L = 0.22 mH, peak I <sub>L</sub> = 30 A)	100		mJ

The following table shows the thermal and mechanical characteristics of the MSC030SDA120B device.

**Table 2 • Thermal and Mechanical Characteristics**

Symbol	Characteristic	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance		0.4	0.58	$^{\circ}\text{C/W}$
$W_T$	Package weight		0.22		oz
			5.9		g
Torque	Maximum mounting torque			10	lb-in
				1.1	N-m

## 3.2 Electrical Performance

The following table shows the static characteristics of the MSC030SDA120B device.

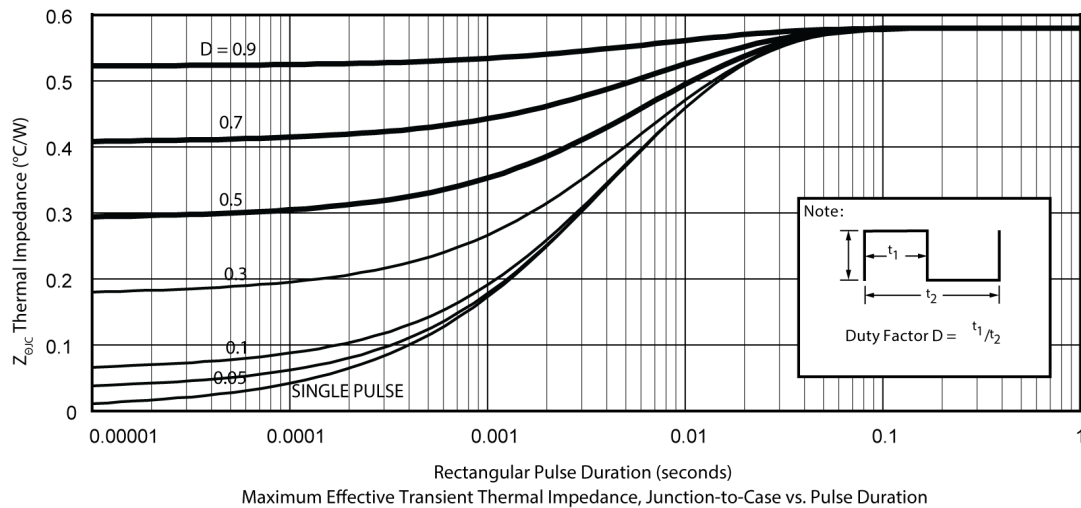
**Table 3 • Static Characteristics**

Symbol	Characteristic/Test Conditions	Min	Typ	Max	Unit
$V_F$	Forward Voltage	$I_F = 30\text{ A}, T_J = 25\text{ }^\circ\text{C}$		1.5	V
		$I_F = 30\text{ A}, T_J = 175\text{ }^\circ\text{C}$		2.1	
$I_{RM}$	Reverse leakage current	$V_R = 1200\text{ V}, T_J = 25\text{ }^\circ\text{C}$		9	$\mu\text{A}$
		$V_R = 1200\text{ V}, T_J = 175\text{ }^\circ\text{C}$		150	
$Q_C$	Total capacitive charge $V_R = 600\text{ V}, T_J = 25\text{ }^\circ\text{C}$			130	nC
$C_J$	Junction capacitance $V_R = 400\text{ V}, T_J = 25\text{ }^\circ\text{C}, f = 1\text{ MHz}$			141	pF
	Junction capacitance $V_R = 800\text{ V}, T_J = 25\text{ }^\circ\text{C}, f = 1\text{ MHz}$			105	

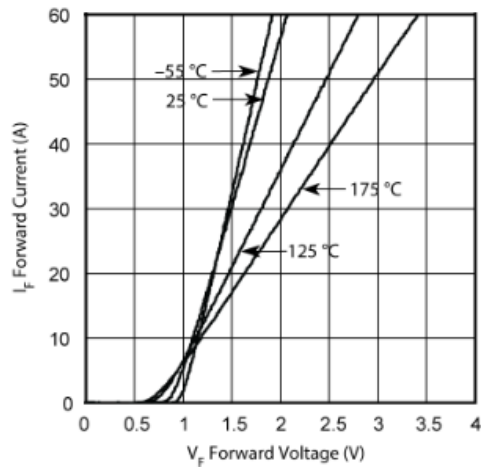
### 3.3 Performance Curves

This section shows the typical performance curves for the MSC030SDA120B device.

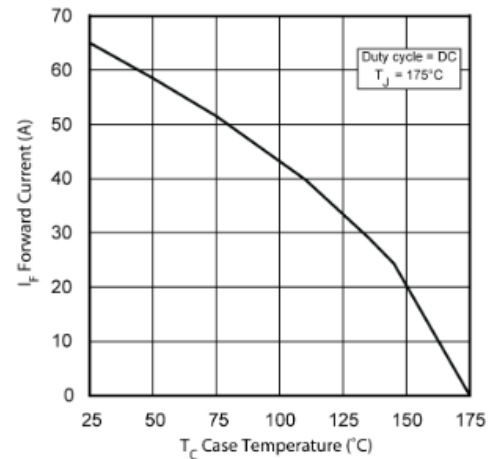
**Figure 1 • Maximum Transient Thermal Impedance**

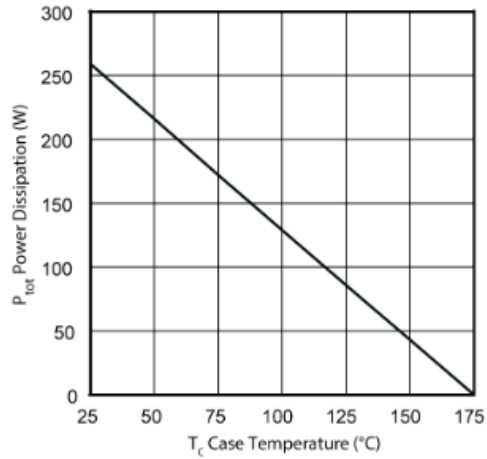
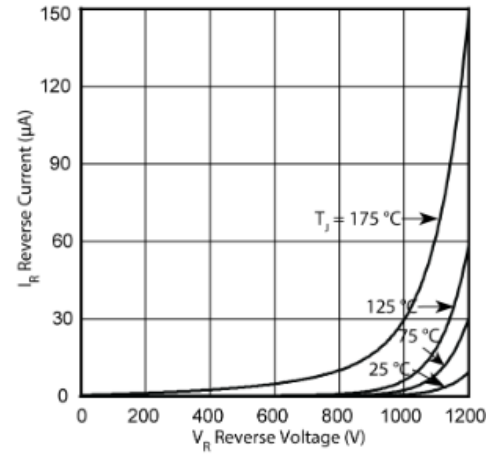
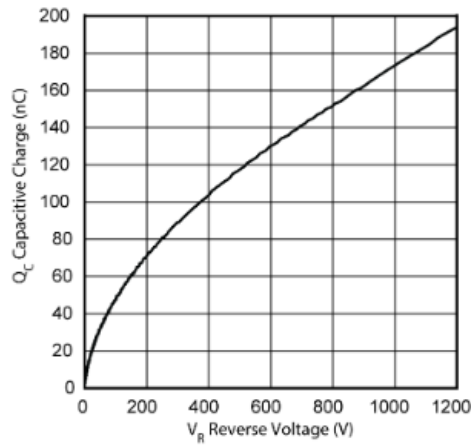
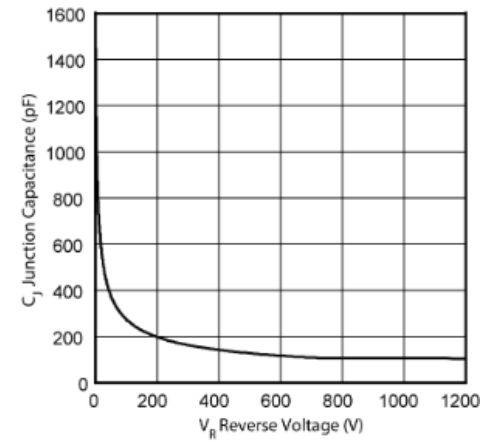


**Figure 2 • Forward Current vs. Forward Voltage**



**Figure 3 • Max Forward Current vs. Case Temp**



**Figure 4 • Max Power Dissipation vs. Case Temp****Figure 5 • Reverse Current vs. Reverse Voltage****Figure 6 • Total Capacitive Charge vs. Reverse Voltage****Figure 7 • Junction Capacitance vs. Reverse Voltage**



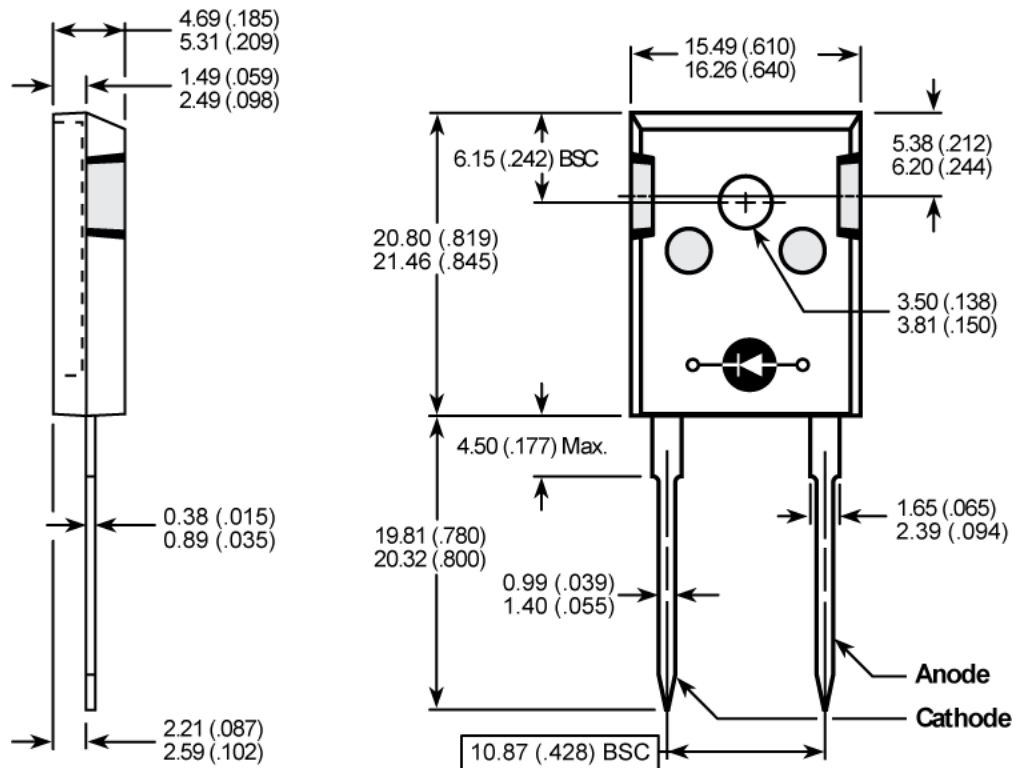
## 4 Package Specification

This section outlines the package specification for the MSC030SDA120B device.

### 4.1 Package Outline Drawing

This section details the TO-247 package drawing of the MSC030SDA120B device. Dimensions are in millimeters and (inches).

**Figure 8 • Package Outline Drawing**



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